

Amendments to the Claims:

Please amend claims 1, 4, 5, 7-9 and 11, and please add new claim 38 as follows:

1. (Currently Amended) A packaged microelectronic device, comprising:
an image sensor die having a first side with a bond-pad, an active area on the
first side, and a second side opposite the first side;
a radiation transmissive window attached to the first side of the die and
positioned over the active area; and
a lead mounted to the second side of the image sensor die and electrically
coupled to the bond-pad.

2. (Original) The device of claim 1, further comprising a casing over the
bond-pad, at least a portion of the second side of the image sensor die, and at least a
portion of the lead.

3. (Original) The device of claim 1, further comprising a casing over the
bond-pad, at least a portion of the second side of the image sensor die, and a portion of
the lead; and

wherein the lead includes an end external to the casing.

4. (Currently Amended) A packaged microelectronic device, comprising:
an image sensor die having a first side with a bond-pad, an active area on the
first side, and a second side opposite the first side;
a radiation transmissive window positioned over the active area;
a lead mounted to the second side of the image sensor die and electrically
coupled to the bond-pad;~~The device of claim 1, further comprising:~~
a casing over the bond-pad, at least a portion of the second side of the image
sensor die, and at least a portion of the lead; and
a solder ball electrically coupled to the lead.

5. (Currently Amended) A packaged microelectronic device, comprising:
an image sensor die having a first side with a bond-pad, an active area on the
first side, and a second side opposite the first side;
a radiation transmissive window positioned over the active area;
a lead mounted to the second side of the image sensor die and electrically
coupled to the bond-pad; and

~~The device of claim 1, further comprising~~ a casing over at least a portion of the
second side of the image sensor die;

wherein the lead includes a first end and a second end opposite the first end;
wherein the first and second ends are covered by the casing; and
wherein a portion of the lead between the first and second ends is exposed to an
ambient environment.

6. (Original) The device of claim 1 wherein the lead is coupled to the second
side of the image sensor die by a lead-on-chip tape.

7. (Currently Amended) A packaged microelectronic device, comprising:
an image sensor die having a first side with a bond-pad, an active area on the
first side, and a second side opposite the first side;
a radiation transmissive window positioned over the active area;
a lead mounted to the second side of the image sensor die and electrically
coupled to the bond-pad; and~~The device of claim 1, further comprising~~
a casing over at least a portion of the second side of the image sensor die;
wherein the lead includes a first portion attached to the second side of the image
sensor die and a second portion at least proximate to the first portion;
wherein the casing has a recess exposing the second portion of the lead to an
ambient environment; and
wherein the recess defines an axis that intersects the window and the image
sensor die.

8. (Currently Amended) A packaged microelectronic device, comprising:
an image sensor die having a first side with a bond-pad, an active area on the
first side, and a second side opposite the first side;
a radiation transmissive window positioned over the active area;
a lead mounted to the second side of the image sensor die and electrically
coupled to the bond-pad; and~~The device of claim 1, further comprising~~
a casing over at least a portion of the second side of the image sensor die and a
portion of the lead;
wherein the lead includes a first portion attached to the image sensor die and a
second portion spaced apart from the first portion; and
wherein the casing includes a recess exposing the second portion of the lead for
attachment to a substrate.

9. (Currently Amended) A packaged microelectronic device, comprising:
an image sensor die having a first side with a bond-pad, an active area on the
first side, and a second side opposite the first side;
a radiation transmissive window positioned over the active area; and
a lead mounted to the second side of the image sensor die and electrically
coupled to the bond-pad;~~The device of claim 1 wherein:~~
wherein the window includes a first side and a second side attached to the image
sensor die and opposite the first side; and
wherein the device further comprises a removable protective covering over at
least a portion of the first side of the window.

10. (Original) The device of claim 1 wherein the window is attached to the
image sensor die with an adhesive.

11. (Currently Amended) A packaged microelectronic device, comprising:
an image sensor die having a first side with an active area, a plurality of bond-
pads on the first side, and a second side opposite the first side;

a radiation transmissive member juxtaposed to the first side of the image sensor die;
a plurality of leads carried by the second side of the image sensor die and electrically coupled to corresponding bond-pads; and
a casing covering the bond-pads, at least a portion of the second side of the image sensor die, and at least a portion of the individual leads.

12. (Original) The device of claim 11 wherein the leads include an end external to the casing.

13. (Original) The device of claim 11, further comprising:
a plurality of ball-pads on corresponding leads; and
a plurality of solder balls on corresponding ball-pads;
wherein the leads are not exposed to an ambient environment.

14. (Original) The device of claim 11 wherein:
the leads include a first end and a second end opposite the first end;
the first and second ends are covered by the casing; and
a portion of the leads between the first and second ends are exposed to an ambient environment.

15. (Original) The device of claim 11 wherein the leads are attached to the second side of the image sensor die by a lead-on-chip tape.

16. (Original) The device of claim 11 wherein:
the leads include a first portion attached to the second side of the image sensor die and a second portion at least proximate to the first portion;
the casing has a plurality of recesses exposing the second portion of the leads;
and
the recesses define a plurality of axes that intersect the window and the image sensor die.

17. (Original) The device of claim 11 wherein:
the leads include a first portion attached to the image sensor die and a second portion spaced apart from the first portion; and
the casing includes a plurality of recesses exposing the second portion of the leads for attachment to a substrate.

18. (Original) The device of claim 11 wherein:
the window includes a first side and a second side opposite the first side, the second side being attached to the image sensor die; and
the device further comprises a removable protective covering over at least a portion of the first side of the window.

19. (Original) The device of claim 11 wherein the leads include a portion external to the casing, the portion having an arcuate configuration.

20. (Original) The device of claim 11 wherein the leads include a portion external to the casing, the portion having an "L" shaped configuration.

21. (Original) A packaged microelectronic device, comprising:
an image sensor die having a first side with a bond-pad, an active area, and a second side opposite the first side;
a window at the first side of the image sensor die;
a lead mounted to the second side of the image sensor die and electrically coupled to the bond-pad, the lead having a first end and a second end opposite the first end; and
a casing over the bond-pad and at least a portion of the second side of the image sensor die, wherein at least a portion of the second end of the lead is exposed through the casing.

22. (Original) The device of claim 21 wherein:
the lead further includes a first portion attached to the second side of the image sensor die and a second portion at least proximate to the first portion;
the casing has a recess exposing the second portion of the lead; and
the recess defines an axis that intersects the window and the image sensor die.

23. (Original) The device of claim 21 wherein the lead is attached to the second side of the image sensor die by a lead-on-chip tape.

24. (Original) The device of claim 21 wherein:
the window includes a first side and a second side opposite the first side, the second side being attached to the image sensor die; and
the device further comprises a removable protective covering over at least a portion of the first side of the window.

25. (Original) The device of claim 21 wherein the second end of the lead has an arcuate configuration.

26. (Original) The device of claim 21 wherein the second end of the lead has an "L" shaped configuration.

27. (Original) A method for packaging a microelectronic device including an image sensor die having a first side with a bond-pad, an active area, and a second side opposite the first side, the method comprising:

attaching a radiation transmissive window to the first side of the image sensor die;
mounting a lead to the second side of the image sensor die;
electrically coupling the bond-pad to the lead; and
encapsulating at least a portion of the lead and at least a portion of the second side of the image sensor die with a casing.

28. (Original) The method of claim 27, further comprising attaching a removable protective covering over at least a portion of the window.

29. (Original) The method of claim 27 wherein the lead includes an end, and wherein encapsulating at least a portion of the lead comprises covering the portion of the lead with the casing without covering the end of the lead.

30. (Original) The method of claim 27, further comprising:
forming a ball-pad on the lead; and
placing a solder ball on the ball-pad.

31. (Original) The method of claim 27 wherein the lead includes a first end and a second end opposite the first end, and wherein encapsulating at least a portion of the lead comprises covering the first and second ends of the lead with the casing without covering a portion of the lead between the first and second ends.

32. (Original) The method of claim 27 wherein:
the lead includes a first portion and a second portion at least proximate to the first portion, the first portion being attached to the second side of the image sensor die; and
encapsulating at least a portion of the lead comprises covering the portion of the lead with the casing without covering the second portion of the lead.

33. (Original) The method of claim 27 wherein coupling the lead to the image sensor die comprises attaching the lead to the image sensor die with a lead-on-chip tape.

34. (Original) A method for packaging a microelectronic device, comprising:
positioning a window at an active area of a first side of an image sensor die;
mounting a lead to a second side of the image sensor die opposite the first side;

electrically coupling a bond-pad on the first side of the image sensor die to the lead;
disposing the window, the image sensor die, and the lead in a mold cavity; and
injecting a mold compound into the mold cavity to encapsulate at least a portion
of the image sensor die.

35. (Original) The method of claim 34 wherein disposing the window, the image sensor die, and the lead in the mold cavity comprises applying a force to the lead to press the window against a wall of the mold cavity.

36. (Original) The method of claim 34, further comprising:
removing the window, the image sensor, and the lead from the mold cavity as a unit;
forming a ball-pad on the lead; and
placing a solder ball on the ball-pad.

37. (Original) The method of claim 34, further comprising attaching a removable protective covering over the window before disposing the window in the mold cavity.

38. (New) The device of claim 11 wherein the radiation transmissive member comprises a window.